

## Intel Unleashed: Engineering the Future

### Key Quotes from Intel CEO Pat Gelsinger

March 23, 2021 — Today, Intel CEO Pat Gelsinger outlined the company's path forward to manufacture, design and deliver leadership products and create long-term value for stakeholders. During the company's global "Intel Unleashed: Engineering the Future" webcast, Gelsinger shared his vision for "IDM 2.0," a major evolution of Intel's integrated device manufacturing (IDM) model. Here are excerpts from his webcast remarks:

#### Overview

- "Our team is fired up, and I have full confidence that Intel is in a very strong competitive position and our best days are ahead."
- "We are the only company with the depth and breadth of software, silicon and platforms, packaging and process with at-scale manufacturing our customers depend on for their next-generation innovations."
- "We are focused on four areas to deliver leadership products and digital innovations in the years ahead: one, be the leader in every category in which we compete; two, execute flawlessly to our commitments; three, passionately innovate with boldness and speed; and four, reignite our culture to attract and motivate the best engineers and technologists on the planet."
- "There is a renewed sense of energy and excitement inside Intel that is building – excitement that our employees, partners and customers are not only seeing but echoing. Our customers and partners want Intel to win, want more of what we provide and are eager to deepen our engagements. Today is the first step, and we are just getting started."

#### IDM 2.0 Vision

- I am excited to share the next major evolution of Intel's integrated device manufacturer or 'IDM' model. I call it IDM 2.0."
- "We have always been in the business of defying physics and building the future, and that's not going to change."
- "First, Intel's internal factory network. Integrated manufacturing has been foundational to our success, enabling product optimization, improved economics, and supply resilience. ... As I mentioned on the January earnings call, we will continue to build the majority of our products in Intel fabs. ... The world will move from system-on-chip to 'system-on-package,' and Intel's unquestioned leadership in packaging technologies becomes even more valuable."
- "Second, we will also expand our use of third-party foundry capacity across our portfolio to deliver the best products in every category that we participate in."
- "Our IDM 2.0 model has an important, third element. Today, I'm announcing our plans to be a world-class foundry business and major provider of U.S.- and European-based capacity to serve customers globally."

#### Intel Foundry Services

- “A key challenge is access to manufacturing capacity. Intel is in a unique position to rise to the occasion and meet this growing demand while ensuring a sustainable and secure supply of semiconductors for the world.”
- “We are establishing Intel Foundry Services – a fully vertical, standalone foundry business, reporting directly to me.”
- “We conservatively size the foundry opportunity as a \$100 billion addressable market by 2025.”
- “We have already received enormous enthusiasm and statements of support from across the industry.”
- “I’m thrilled to announce plans for Intel’s first large-scale foundry operation, which will be in Arizona. ... These fabs will support expanding requirements of our current products and customers and provide committed capacity for foundry customers.”
- “I expect that we will be ready to announce our next phase of expansions in the U.S., Europe and other global locations within the year.”
- “We will be differentiated from other foundry offerings with a combination of leading-edge packaging and process technology, committed capacity in the U.S. and Europe – available for customers globally – and a world-class IP portfolio that customers can choose from, including x86 cores, graphics, media, display, AI, interconnect, fabric and other critical foundational IP, along with ARM and RISC-V ecosystem IPs.”
- “Intel Foundry Services will also provide access to silicon design services to help our customers seamlessly turn silicon into solutions, using industry standard design packages.”

## 7 Nanometer Progress

- “Our confidence in 7nm health and competitiveness is accelerating.”
- “We’ve rearchitected and simplified our 7nm process flow, increasing our use of EUV by more than 100%.”
- “Leveraging our 7nm process, we are advancing the development of lead data center and client CPUs – starting with ‘Meteor Lake,’ our high-volume 2023 client product. In fact, we expect to tape in our 7nm compute tile for Meteor Lake in the second quarter of this year.”

## Research Collaboration with IBM

- “I am proud to announce plans for a new research collaboration with IBM focused on advanced silicon process and packaging technology.”
- “This collaboration puts two of the best semiconductor research organizations together to accelerate the velocity of packaging and process innovations into the future.”

## Product Roadmap Update

- “We expect that in the third quarter of this year, the majority of our client CPU wafer starts will be on 10nm, including our Superfin process.”
- “In two weeks, we’ll officially launch our new 3rd Gen Xeon Scalable Processors, or ‘Ice Lake.’”
- “We have customers testing ‘Sapphire Rapids’ now, and we’ll look to reach production around the end of the year, ramping in the first half of 2022.”
- Intel’s 2023 CPU product roadmap: “It includes Meteor Lake for client and ‘Granite Rapids’ for data center. Both Meteor Lake and Granite Rapids will have compute tiles built on Intel 7nm.”

- “For our 2023 roadmap, we will also leverage our relationship with TSMC to deliver additional leadership CPU products for our client and data center customers. This is the power of our new IDM 2.0 model combined with a modular approach to design and Intel’s industry leading packaging technologies.”

## About Intel

Intel (Nasdaq: INTC) is an industry leader, creating world-changing technology that enables global progress and enriches lives. Inspired by Moore’s Law, we continuously work to advance the design and manufacturing of semiconductors to help address our customers’ greatest challenges. By embedding intelligence in the cloud, network, edge and every kind of computing device, we unleash the potential of data to transform business and society for the better. To learn more about Intel’s innovations, go to [newsroom.intel.com](https://newsroom.intel.com) and [intel.com](https://intel.com).

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